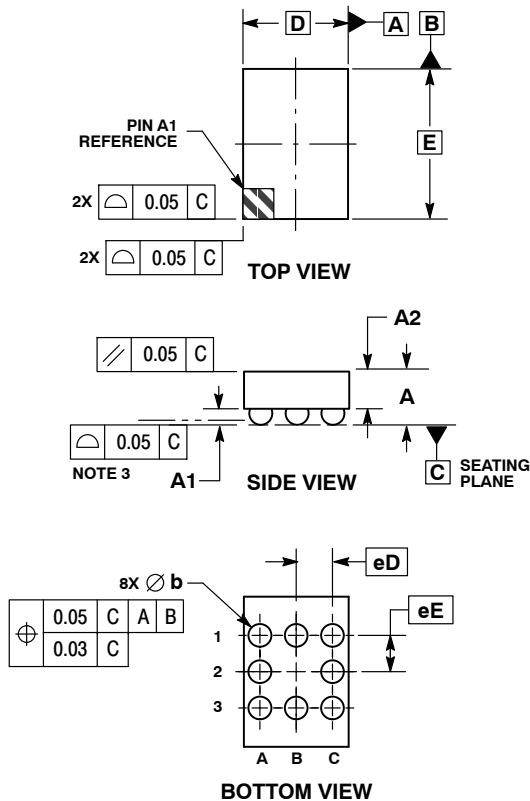




SCALE 4:1

**WLCSP8, 1.155x1.655**  
CASE 567DH  
ISSUE O

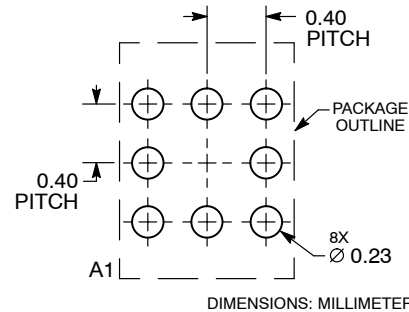
DATE 12 JAN 2012



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.50	0.60
A1	0.17	0.24
A2	0.36 REF	
b	0.24	0.29
D	1.155 BSC	
E	1.655 BSC	
eD	0.40 BSC	
eE	0.40 BSC	

**RECOMMENDED  
SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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